

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/10/2022

Details for "TPSS4262QPWPRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS54262QPWPRQ1	NIPDAU	Level-3-260C-168 HR	TI TAIWAN A/T	PWP 20	4.4x6.5x1.15	80.5

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000165	2	0.000001	0
Other Nonferrous Metals and Alloys	Beryllium	7440-41-7	0.000001	0.000165	2	0.000001	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000001	0.000165	2	0.000001	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000004	0.000661	7	0.000005	0
Precious Metals	Gold	7440-57-5	0.60553	99.997688	999977	0.752549	7525
Precious Metals	Silver	7440-22-4	0.000007	0.001156	12	0.000009	0
Sub-Total			0.605544	100	1000000	0.752567	7526
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.341839	85.000006	850000	1.66763	16676
Thermoplastics	Epoxy	85954-11-6	0.236795	14.999994	150000	0.294288	2943
Sub-Total			1.578634	100	1000000	1.961918	19619
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	31.827579	97.424999	974250	39.555142	395551
Copper and Its Alloys	Iron	7439-89-6	0.784051	2.399999	24000	0.974414	9744
Copper and Its Alloys	Phosphorus	7723-14-0	0.0049	0.014999	150	0.00609	61
Copper and Its Alloys	Tin	7440-31-5	0.009801	0.030001	300	0.012181	122
Copper and Its Alloys	Zinc	7440-66-6	0.032669	0.100001	1000	0.040601	406
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.009801	0.030001	300	0.012181	122
Sub-Total			32.668801	100	1000000	40.600608	406006
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.47808	90	900000	0.594155	5942
Precious Metals	Gold	7440-57-5	0.01328	2.5	25000	0.016504	165
Precious Metals	Palladium	7440-05-3	0.03984	7.5	75000	0.049513	495
Sub-Total			0.5312	100	1000000	0.660172	6602
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	34.613361	85	850000	43.017297	430173
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	0.488659	1.199999	12000	0.607303	6073
Other Plastics and Rubber	Carbon Black	1333-86-4	0.122165	0.3	3000	0.151826	1518
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.122165	0.3	3000	0.151826	1518
Other Plastics and Rubber	Silicone	218163-11-2	1.221648	3	30000	1.518257	15183
Thermoplastics	Epoxy	85954-11-6	4.153603	10.199999	102000	5.162075	51621
Sub-Total			40.721601	100	1000000	50.608584	506086
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	4.358042	100	1000000	5.416151	54162
Sub-Total			4.358042	100	1000000	5.416151	54162
Total			80.463822			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.